

**MATERIAL:**  
 Housing: LCP, 94V-0, Black  
 Contact: Copper Alloy  
 Latch: Stainless Steel; 50u" Nickel Subplate; 100u" Matte Tin Overall  
 Contact Plating: Specified Au thickness in Contact area; Au Flash on remaining area ;50u" min Nickel subplate

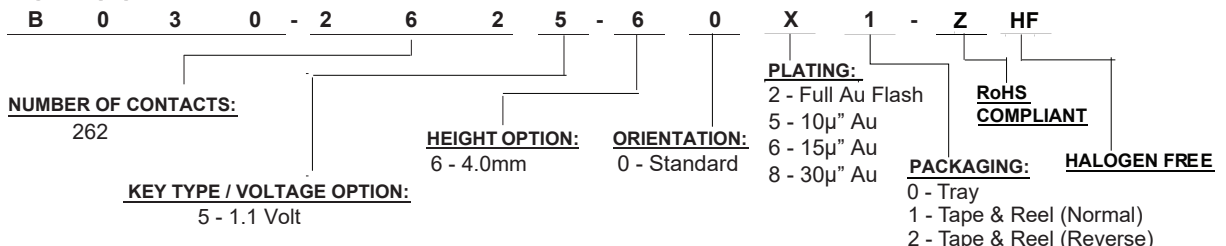
Recommended Stencil Thickness : 0.12 min.  
 Reflow Compatible : 260 C max for 10 sec.

**MECHANICAL:**  
 Insertion Force: 59.8 N max.  
 Durability: 25 Cycles  
 Shock: Pass EIA -364-27  
 Vibration: Pass EIA -364-28

**ELECTRICAL:**  
 Current Rating : 0.5 A  
 Voltage Rating : 1.1 V  
 Contact Resistance: 40 milliohms initial; 20 milliohm max change  
 Insulation Resistance : 1 Megaohm min at 500V DC  
 Dielectric Withstanding Voltage: 250 VAC min for 1 minute

**ENVIRONMENTAL:**  
 Operating Temperature: -55 C to 85 C  
 Solderability: Pass JESD22-B102 C  
 Humidity : Pass EIA 364-21  
 Thermal Shock :EIA-364-32, Method A, Table 2 Test Condition 1  
 Salt Spray : 48 H

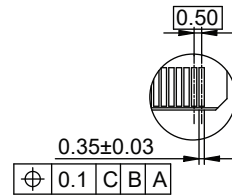
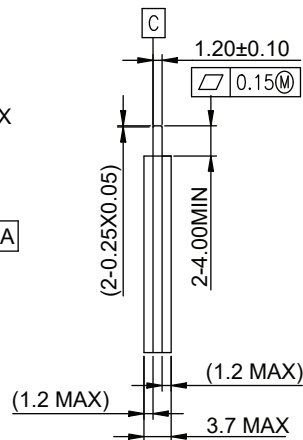
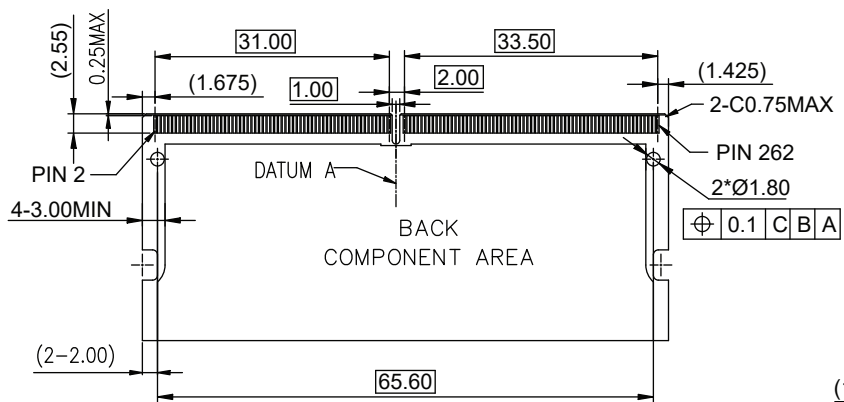
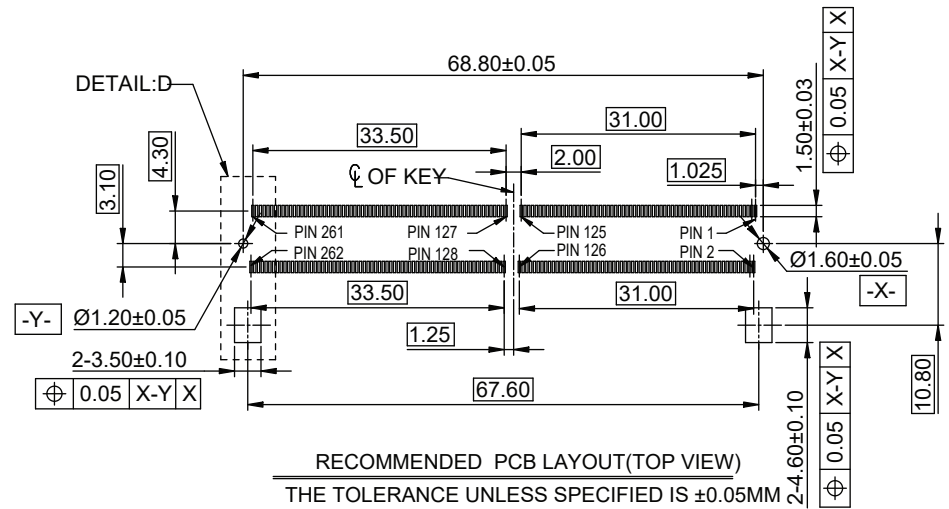
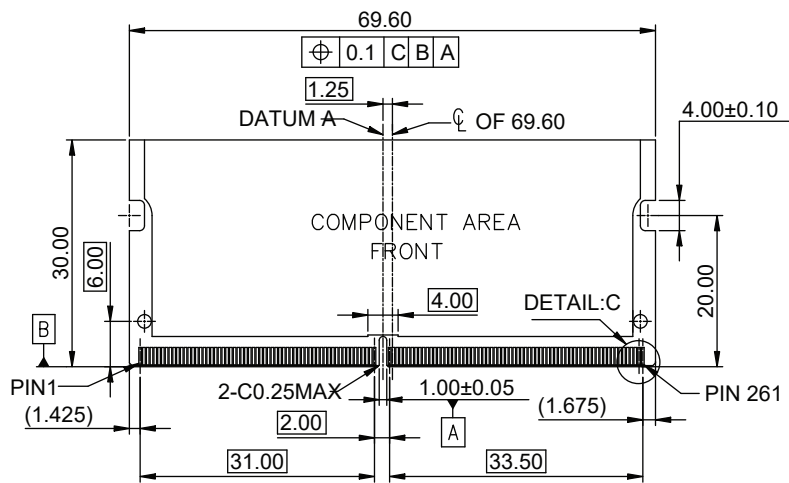
**HOW TO ORDER:**



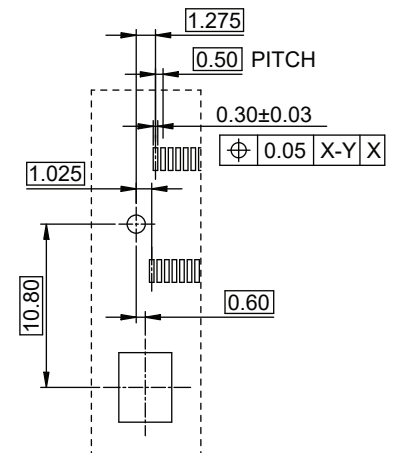
Rev	Drawn	Checked	Approved	Date
0	B.S.	S.M.	S.M.	06/24/25

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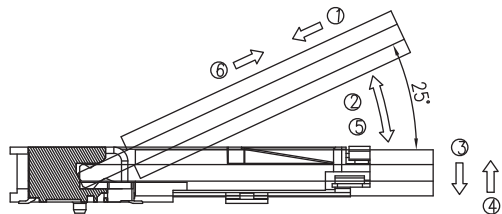
DDR 5 SO DIMM Socket, 262 Position, 1.1Volt,  
 Standard Orientation, 4.0mm Height,



DETAIL:C  
SCALE 2:1



DETAIL:D  
SCALE 2:1

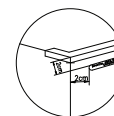
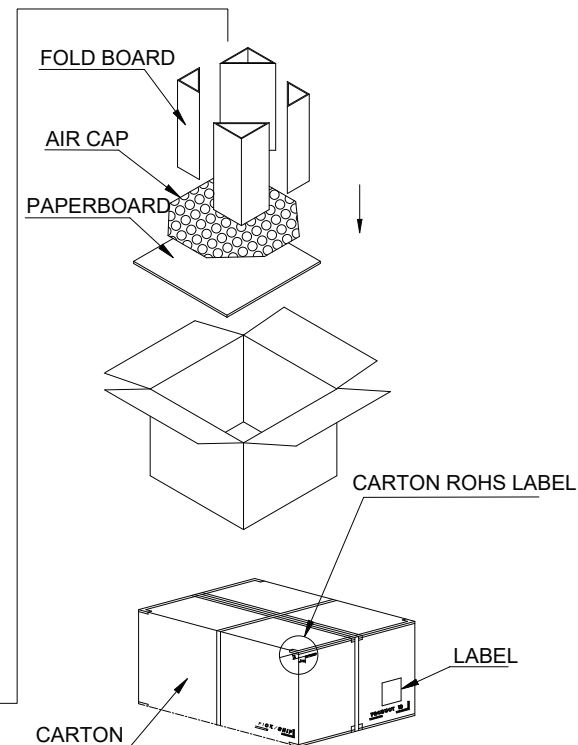
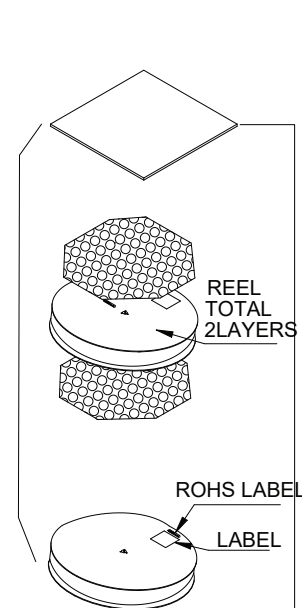
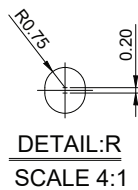
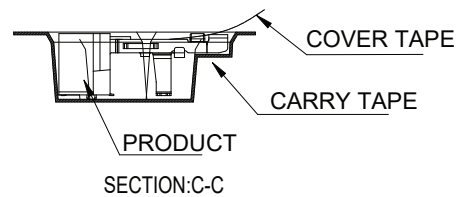
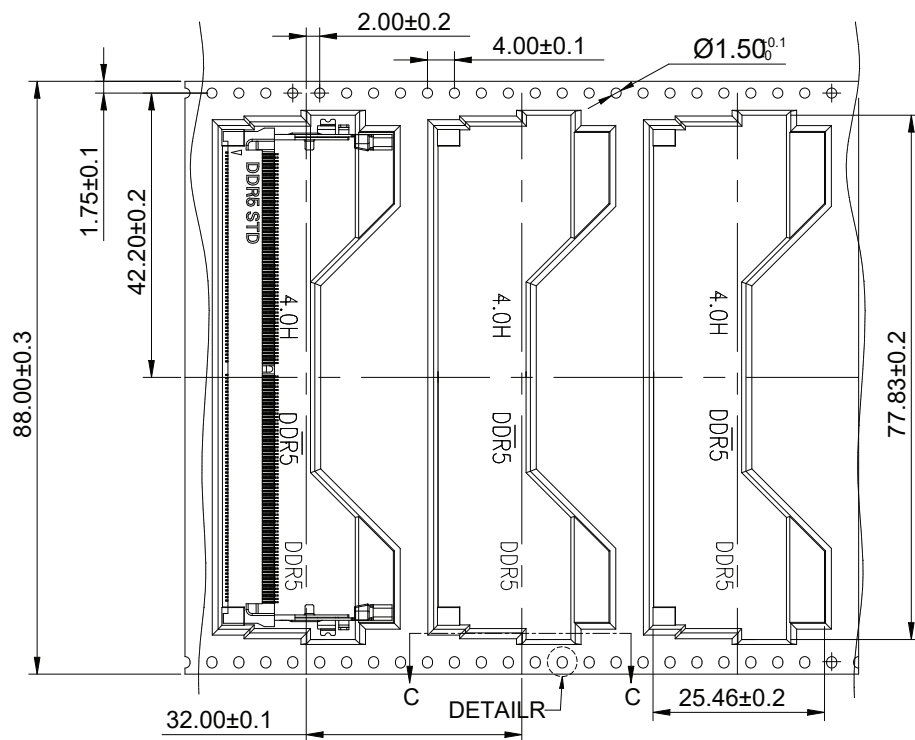
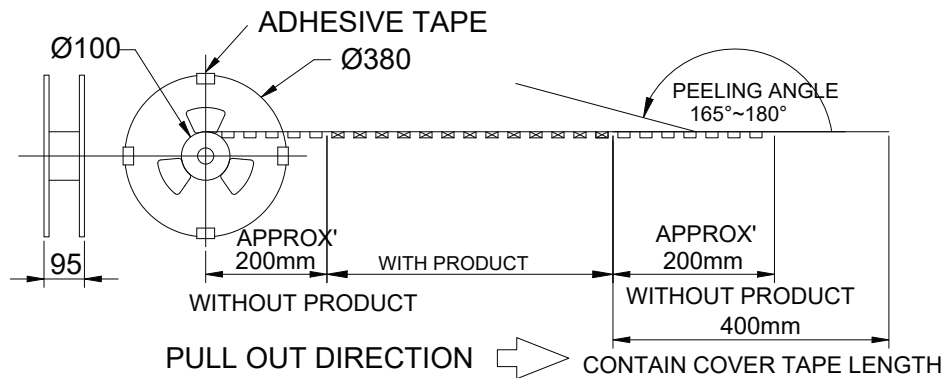


MATING/UNMATING VIEW  
SCALE 2:1

MATING: ① INSERTING(30°) — ② ROTATING — ③ FIXED  
UNMATING: ④ UNFIXED — ⑤ ROTATING — ⑥ WITHDRAWING

**SMP TECHNOLOGY, INC.**

DDR 5 SO DIMM Socket, 262 Position, 1.1Volt,  
Standard Orientation, 4.0mm Height,



500	2	1000	SEE P/N
PCS/ REEL	REEL/ CARTON	PCS/ CARTON	PART NUMBER

**SMP TECHNOLOGY, INC.**

DDR 5 SO DIMM Socket, 262 Position, 1.1Volt,  
Standard Orientation, 4.0mm Height,